# MA27V03

### Silicon epitaxial planar type

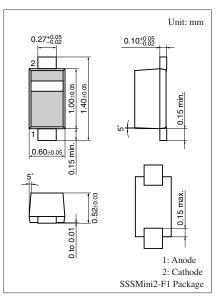
#### For VCO

#### Features

- $\bullet$  Good linearity and large capacitance-ratio in  $C_D$   $V_R$  relation
- Small series resistance r<sub>D</sub>
- SSS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V <sub>R</sub>	6	V
Junction temperature	Tj	125	°C
Storage temperature	T <sub>stg</sub>	-55 to +125	°C



Marking Symbol: 3

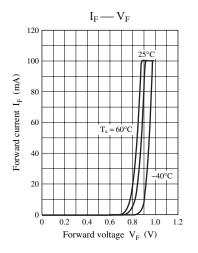
#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

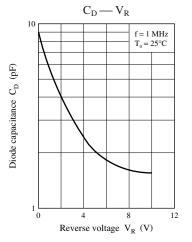
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	I <sub>R</sub>	$V_R = 5 V$			10	nA
Diode capacitance	C <sub>D(1V)</sub>	$V_R = 1 V, f = 1 MHz$	5.20		5.80	pF
	C <sub>D(4V)</sub>	$V_R = 4 V, f = 1 MHz$	2.10		2.58	
Capacitance ratio	C <sub>D(1V)</sub> /C <sub>D(4V)</sub>		2.1		2.6	
Series resistance *	r <sub>D</sub>	$V_{R} = 4 V, f = 470 MHz$			0.3	Ω

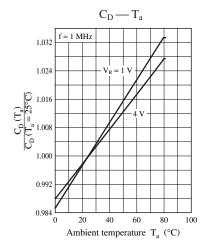
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

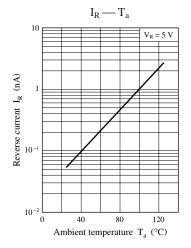
2. Absolute frequency of input and output is 470 MHz.

3. \*: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER









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